

CHE323/CHE384  
Chemical Processes for Micro- and Nanofabrication  
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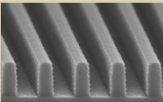
**Lecture 49**  
**Lithography:**  
**DNQ Photoresists**

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## Photoresist

- Photoresist Tasks
  - Form an image (“photo”)
  - Resist etch/implant (“resist”)
- Photoresist Components
  - Photoactive Compound (PAC)/Sensitizer
  - Polymer Resin
  - Solvent
- Conventional Resist: DNQ/Novolac (g-line, i-line)
- Modern Resist: Chemically Amplified (248, 193 nm)



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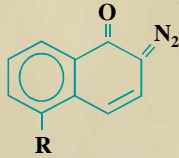
## Resist Types

- Cross-linking Negative Resist
  - Exposure causes a cross-linking agent to react with polymer, increasing the molecular weight
- Conventional (DNQ/Novolac) Resist
  - Exposure generates product which causes a direct change in the resist solubility
- Chemically Amplified Resist
  - Exposure generates acid, but does not directly affect dissolution rate (needs a post-exposure bake)
  - More on this later

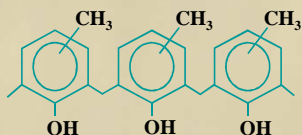
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## DNQ/Novolac Resist

Diazonaphthoquinone (DNQ)  
(sensitizer or PAC)



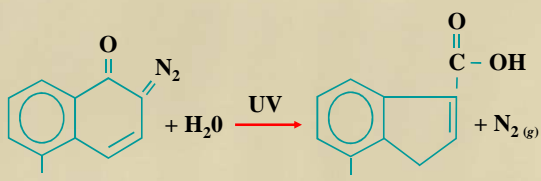
Novolac Resin



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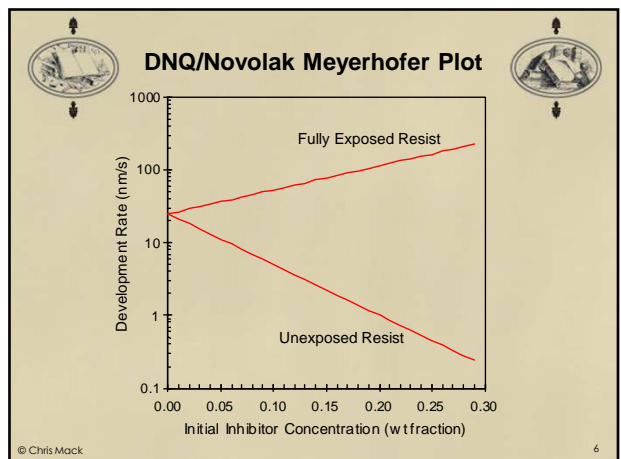
## Exposure Reaction

$M \xrightarrow{UV} P$



Diazonaphthoquinone (dissolution inhibitor) Carboxylic Acid (dissolution enhancer)

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## Exposure Kinetics

- Kinetics: the study of how fast a reaction proceeds

First Order Kinetics:  $\frac{dM}{dt} = -CIM$

where  $M$  = Sensitizer Concentration  
 $I$  = Light Intensity  
 $t$  = Exposure Time  
 $C$  = Exposure Rate Constant

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## Exposure Kinetics

If  $I$  is constant with time,

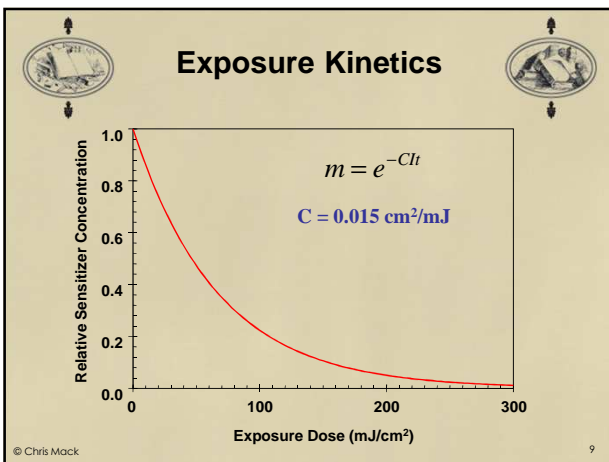
$$M = M_o \exp(-CIt)$$

$M_o$  = initial (unexposed) sensitizer concentration

$$m = \frac{M}{M_o} = \exp(-CIt)$$

relative sensitizer concentration  $It$  = exposure dose

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## Reciprocity

- For first-order exposure kinetics, resist exposure exhibits reciprocity
  - Neither light intensity nor exposure time matter; only their product (dose) affects the amount of chemical change
  - Lithography tools control exposure by controlling the integrated dose, allowing intensity to vary
    - Mercury arc lamps decrease in intensity with time
    - Excimer lasers exhibit pulse-to-pulse energy variations

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## Lecture 49: What have we Learned?

- What are the two main tasks of a photoresist?
- What are the three major components of a photoresist?
- Name three types of photoresists that have been used in semiconductor manufacturing
- How does DNQ exposure affect resist solubility in developer?
- What is reciprocity?

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